



#4

Supplemental Declaration for Patent Application English Language Declaration

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am an original, first and joint inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled

MODULAR ASSEMBLY OF ANTIBODY GENES, ANTIBODIES PREPARED THEREBY AND USE

the specification of which

(check one)

- ☐ is attached hereto.
- ☒ was filed on August 19, 1994 as
Application Serial No. 08/299,085
and was amended on _____
(if applicable)

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, §1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, §119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s)

Priority Claimed

(Number) (Country) (Day Month Year Filed)

☐ Yes ☐ No

(Number) (Country) (Day Month Year Filed)

☐ Yes ☐ No

I hereby claim the benefit under Title 35, United States Code, §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, §1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application.

07/987,555
(Application Serial No.)

12/08/92
(Filing Date)

abandoned
(Status)
(patented, pending, abandoned)

07/501,092 (Application Serial No.)	03/29/90 (Filing Date)	abandoned (Status) (patented, pending, abandoned)
07/077,528 (Application Serial No.)	07/24/87 (Filing Date)	abandoned (Status) (patented, pending, abandoned)
PCT/US86/02269 (Application Serial No.)	10/27/86 (Filing Date)	abandoned (Status) (patented, pending, abandoned)
06/793,980 (Application Serial No.)	11/01/85 (Filing Date)	abandoned (Status) (patented, pending, abandoned)
07/142,039 (Application Serial No.)	01/11/88 (Filing Date)	abandoned (Status) (patented, pending, abandoned)

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of first inventor, if any Randy R. Robinson	
First Inventor's signature <i>Randy R. Robinson</i>	Date Nov. 11, 1995
Residence 133 Firestone Drive, Walnut Creek, California 94598	
Citizenship U.S.A.	
Post Office Address Same as residence	

Full name of second inventor, if any Alvin Y. Liu	
Second Inventor's signature	Date
Residence 4246 11 th Avenue, N.E., # 311, Seattle, WA 98105	
Citizenship U.S.A.	
Post Office Address Same as residence	
Full name of third inventor, if any Arnold H. Horwitz	
Third Inventor's signature	Date
Residence 7529 Midfield Avenue, Los Angeles, California 90045	
Citizenship U.S.A.	
Post Office Address Same as residence	
Full name of fourth inventor, if any Marc Better	
Fourth Inventor's signature	Date
Residence 2462 Zorada Drive, Los Angeles, California 90046	
Citizenship U.S.A.	
Post Office Address Same as residence	

Full name of fifth inventor, if any Randolph Wall	
Fifth Inventor's signature	Date
Residence 5106 Van Noord, Sherman Oaks, California 91423	
Citizenship U.S.A.	
Post Office Address Same as residence	
Full name of sixth inventor, if any Shau-Ping Lei	
Sixth Inventor's signature	Date
Residence 11452 Clarkson Road, Los Angeles, California 90064	
Citizenship ROC	
Post Office Address Same as residence	
Full name of seventh inventor, if any Gary L. Wilcox	
Seventh Inventor's signature	Date
Residence 2007 - 148th Street, S.E., Mill Creek, Washington 98012	
Citizenship U.S.A.	
Post Office Address Same as residence	

(Supply similar information and signature for subsequent joint inventors, if any)



Supplemental Declaration for Patent Application
English Language Declaration

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am an original, first and joint inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled

MODULAR ASSEMBLY OF ANTIBODY GENES, ANTIBODIES PREPARED THEREBY AND USE

the specification of which

(check one)

☐ is attached hereto.

☒ was filed on August 19, 1994 as
Application Serial No. 08/299,085
and was amended on _____
(if applicable)

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, §1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, §119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s)			Priority Claimed	
_____ (Number)	_____ (Country)	_____ (Day Month Year Filed)	<input type="checkbox"/> Yes	<input type="checkbox"/> No
_____ (Number)	_____ (Country)	_____ (Day Month Year Filed)	<input type="checkbox"/> Yes	<input type="checkbox"/> No

I hereby claim the benefit under Title 35, United States Code, §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, §1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application.

07/987,555
(Application Serial No.)

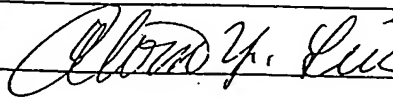
12/08/92
(Filing Date)

abandoned
(Status)
(patented, pending, abandoned)

<u>07/501,092</u> (Application Serial No.)	<u>03/29/90</u> (Filing Date)	<u>abandoned</u> (Status) (patented, pending, abandoned)
<u>07/077,528</u> (Application Serial No.)	<u>07/24/87</u> (Filing Date)	<u>abandoned</u> (Status) (patented, pending, abandoned)
<u>PCT/US86/02269</u> (Application Serial No.)	<u>10/27/86</u> (Filing Date)	<u>abandoned</u> (Status) (patented, pending, abandoned)
<u>06/793,980</u> (Application Serial No.)	<u>11/01/85</u> (Filing Date)	<u>abandoned</u> (Status) (patented, pending, abandoned)
<u>07/142,039</u> (Application Serial No.)	<u>01/11/88</u> (Filing Date)	<u>abandoned</u> (Status) (patented, pending, abandoned)

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of first inventor, if any Randy R. Robinson	
First Inventor's signature	Date
Residence 133 Firestone Drive, Walnut Creek, California 94598	
Citizenship U.S.A.	
Post Office Address Same as residence	

Full name of second inventor, if any Alvin Y. Liu	
Second Inventor's signature 	12/1/95 Date
Residence 4746 11 th Avenue, N.E., # 311, Seattle, WA 98105	
Citizenship U.S.A.	
Post Office Address Same as residence	
Full name of third inventor, if any Arnold H. Horwitz	
Third Inventor's signature	Date
Residence 7529 Midfield Avenue, Los Angeles, California 90045	
Citizenship U.S.A.	
Post Office Address Same as residence	
Full name of fourth inventor, if any Marc Better	
Fourth Inventor's signature	Date
Residence 2462 Zorada Drive, Los Angeles, California 90046	
Citizenship U.S.A.	
Post Office Address Same as residence	

Full name of fifth inventor, if any Randolph Wall	
Fifth Inventor's signature	Date
Residence 5106 Van Noord, Sherman Oaks, California 91423	
Citizenship U.S.A.	
Post Office Address Same as residence	
Full name of sixth inventor, if any Shau-Ping Lei	
Sixth Inventor's signature	Date
Residence 11452 Clarkson Road, Los Angeles, California 90064	
Citizenship ROC	
Post Office Address Same as residence	
Full name of seventh inventor, if any Gary L. Wilcox	
Seventh Inventor's signature	Date
Residence 2007 - 148th Street, S.E., Mill Creek, Washington 98012	
Citizenship U.S.A.	
Post Office Address Same as residence	

(Supply similar information and signature for subsequent joint inventors, if any)



Supplemental Declaration for Patent Application
English Language Declaration

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am an original, first and joint inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled

MODULAR ASSEMBLY OF ANTIBODY GENES, ANTIBODIES PREPARED THEREBY AND USE

the specification of which

(check one)

☐ is attached hereto.

☒ was filed on August 19, 1994 as
Application Serial No. 08/299,085
and was amended on _____
(if applicable)

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, §1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, §119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s)

Priority Claimed

(Number) (Country) (Day Month Year Filed)

☐ Yes ☐ No

(Number) (Country) (Day Month Year Filed)

☐ Yes ☐ No

I hereby claim the benefit under Title 35, United States Code, §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, §1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application.

07/987,555
(Application Serial No.)

12/08/92
(Filing Date)

abandoned
(Status)
(patented, pending, abandoned)

<u>07/501,092</u> (Application Serial No.)	<u>03/29/90</u> (Filing Date)	<u>abandoned</u> (Status) (patented, pending, abandoned)
<u>07/077,528</u> (Application Serial No.)	<u>07/24/87</u> (Filing Date)	<u>abandoned</u> (Status) (patented, pending, abandoned)
<u>PCT/US86/02269</u> (Application Serial No.)	<u>10/27/86</u> (Filing Date)	<u>abandoned</u> (Status) (patented, pending, abandoned)
<u>06/793,980</u> (Application Serial No.)	<u>11/01/85</u> (Filing Date)	<u>abandoned</u> (Status) (patented, pending, abandoned)
<u>07/142,039</u> (Application Serial No.)	<u>01/11/88</u> (Filing Date)	<u>abandoned</u> (Status) (patented, pending, abandoned)

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of first inventor, if any Randy R. Robinson	
First Inventor's signature	Date
Residence 133 Firestone Drive, Walnut Creek, California 94598	
Citizenship U.S.A.	
Post Office Address Same as residence	

Full name of second inventor, if any Alvin Y. Liu	
Second Inventor's signature	Date
Residence 4246 11 th Avenue, N.E., # 311, Seattle, WA 98105	
Citizenship U.S.A.	
Post Office Address Same as residence	
Full name of third inventor, if any Arnold H. Horwitz	
Third Inventor's signature <i>Arnold H. Horwitz</i>	Date 11/1/95
Residence 7529 Midfield Avenue, Los Angeles, California 90045	
Citizenship U.S.A.	
Post Office Address Same as residence	
Full name of fourth inventor, if any Marc Better	
Fourth Inventor's signature	Date
Residence 2462 Zorada Drive, Los Angeles, California 90046	
Citizenship U.S.A.	
Post Office Address Same as residence	

Full name of fifth inventor, if any Randolph Wall	
Fifth Inventor's signature	Date
Residence 5106 Van Noord, Sherman Oaks, California 91423	
Citizenship U.S.A.	
Post Office Address Same as residence	
Full name of sixth inventor, if any Shau-Ping Lei	
Sixth Inventor's signature	Date
Residence 11452 Clarkson Road, Los Angeles, California 90064	
Citizenship ROC	
Post Office Address Same as residence	
Full name of seventh inventor, if any Gary L. Wilcox	
Seventh Inventor's signature	Date
Residence 2007 - 148th Street, S.E., Mill Creek, Washington 98012	
Citizenship U.S.A.	
Post Office Address Same as residence	

(Supply similar information and signature for subsequent joint inventors, if any)



Supplemental Declaration for Patent Application English Language Declaration

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am an original, first and joint inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled

MODULAR ASSEMBLY OF ANTIBODY GENES, ANTIBODIES PREPARED THEREBY AND USE

the specification of which

(check one)

☐ is attached hereto.

☒ was filed on August 19, 1994 as
Application Serial No. 08/299,085
and was amended on _____
(if applicable)

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, §1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, §119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s)

Priority Claimed

(Number)

(Country)

(Day Month Year Filed)

☐
Yes

☐
No

(Number)

(Country)

(Day Month Year Filed)

☐
Yes

☐
No

I hereby claim the benefit under Title 35, United States Code, §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, §1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application.

07/987,555
(Application Serial No.)

12/08/92
(Filing Date)

abandoned
(Status)
(patented, pending, abandoned)

<u>07/501,092</u> (Application Serial No.)	<u>03/29/90</u> (Filing Date)	<u>abandoned</u> (Status) (patented, pending, abandoned)
<u>07/077,528</u> (Application Serial No.)	<u>07/24/87</u> (Filing Date)	<u>abandoned</u> (Status) (patented, pending, abandoned)
<u>PCT/US86/02269</u> (Application Serial No.)	<u>10/27/86</u> (Filing Date)	<u>abandoned</u> (Status) (patented, pending, abandoned)
<u>06/793,980</u> (Application Serial No.)	<u>11/01/85</u> (Filing Date)	<u>abandoned</u> (Status) (patented, pending, abandoned)
<u>07/142,039</u> (Application Serial No.)	<u>01/11/88</u> (Filing Date)	<u>abandoned</u> (Status) (patented, pending, abandoned)

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of first inventor, if any Randy R. Robinson	
First Inventor's signature	Date
Residence 133 Firestone Drive, Walnut Creek, California 94598	
Citizenship U.S.A.	
Post Office Address Same as residence	

Full name of second inventor, if any Alvin Y. Liu	
Second Inventor's signature	Date
Residence 4246 11 th Avenue, N.E., # 311, Seattle, WA 98105	
Citizenship U.S.A.	
Post Office Address Same as residence	
Full name of third inventor, if any Arnold H. Horwitz	
Third Inventor's signature	Date
Residence 7529 Midfield Avenue, Los Angeles, California 90045	
Citizenship U.S.A.	
Post Office Address Same as residence	
Full name of fourth inventor, if any Marc Better	
Fourth Inventor's signature <i>Marc Better</i>	Date 11-1-95
Residence 2462 Zorada Drive, Los Angeles, California 90046	
Citizenship U.S.A.	
Post Office Address Same as residence	

Full name of fifth inventor, if any Randolph Wall	
Fifth Inventor's signature	Date
Residence 5106 Van Noord, Sherman Oaks, California 91423	
Citizenship U.S.A.	
Post Office Address Same as residence	
Full name of sixth inventor, if any Shau-Ping Lei	
Sixth Inventor's signature	Date
Residence 11452 Clarkson Road, Los Angeles, California 90064	
Citizenship ROC	
Post Office Address Same as residence	
Full name of seventh inventor, if any Gary L. Wilcox	
Seventh Inventor's signature	Date
Residence 2007 - 148th Street, S.E., Mill Creek, Washington 98012	
Citizenship U.S.A.	
Post Office Address Same as residence	

(Supply similar information and signature for subsequent joint inventors, if any)



Supplemental Declaration for Patent Application
English Language Declaration

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am an original, first and joint inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled

MODULAR ASSEMBLY OF ANTIBODY GENES, ANTIBODIES PREPARED THEREBY AND USE

the specification of which

(check one)

- ☐ is attached hereto.
- ☒ was filed on August 19, 1994 as
Application Serial No. 08/299,085
and was amended on _____
(if applicable)

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, §1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, §119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s)

Priority Claimed

(Number) (Country) (Day Month Year Filed)

☐ Yes ☐ No

(Number) (Country) (Day Month Year Filed)

☐ Yes ☐ No

I hereby claim the benefit under Title 35, United States Code, §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, §1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application.

07/987,555
(Application Serial No.)

12/08/92
(Filing Date)

abandoned
(Status)
(patented, pending, abandoned)

<u>07/501,092</u> (Application Serial No.)	<u>03/29/90</u> (Filing Date)	<u>abandoned</u> (Status) (patented, pending, abandoned)
<u>07/077,528</u> (Application Serial No.)	<u>07/24/87</u> (Filing Date)	<u>abandoned</u> (Status) (patented, pending, abandoned)
<u>PCT/US86/02269</u> (Application Serial No.)	<u>10/27/86</u> (Filing Date)	<u>abandoned</u> (Status) (patented, pending, abandoned)
<u>06/793,980</u> (Application Serial No.)	<u>11/01/85</u> (Filing Date)	<u>abandoned</u> (Status) (patented, pending, abandoned)
<u>07/142,039</u> (Application Serial No.)	<u>01/11/88</u> (Filing Date)	<u>abandoned</u> (Status) (patented, pending, abandoned)

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of first inventor, if any Randy R. Robinson	
First Inventor's signature	Date
Residence 133 Firestone Drive, Walnut Creek, California 94598	
Citizenship U.S.A.	
Post Office Address Same as residence	

Full name of second inventor, if any Alvin Y. Liu	
Second Inventor's signature	Date
Residence 4246 11 th Avenue, N.E., # 311, Seattle, WA 98105	
Citizenship U.S.A.	
Post Office Address Same as residence	
Full name of third inventor, if any Arnold H. Horwitz	
Third Inventor's signature	Date
Residence 7529 Midfield Avenue, Los Angeles, California 90045	
Citizenship U.S.A.	
Post Office Address Same as residence	
Full name of fourth inventor, if any Marc Better	
Fourth Inventor's signature	Date
Residence 2462 Zorada Drive, Los Angeles, California 90046	
Citizenship U.S.A.	
Post Office Address Same as residence	

Full name of fifth inventor, if any Randolph Wall	
Fifth Inventor's signature <i>Ram Wall</i>	Date 11/1/95
Residence 5106 Van Noord, Sherman Oaks, California 91423	
Citizenship U.S.A.	
Post Office Address Same as residence	
Full name of sixth inventor, if any Shau-Ping Lei	
Sixth Inventor's signature	Date
Residence 11452 Clarkson Road, Los Angeles, California 90064	
Citizenship ROC	
Post Office Address Same as residence	
Full name of seventh inventor, if any Gary L. Wilcox	
Seventh Inventor's signature	Date
Residence 2007 - 148th Street, S.E., Mill Creek, Washington 98012	
Citizenship U.S.A.	
Post Office Address Same as residence	

(Supply similar information and signature for subsequent joint inventors, if any)



Supplemental Declaration for Patent Application
English Language Declaration

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am an original, first and joint inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled

MODULAR ASSEMBLY OF ANTIBODY GENES, ANTIBODIES PREPARED THEREBY AND USE

the specification of which

(check one)

- ☐ is attached hereto.
- ☒ was filed on August 19, 1994 as
Application Serial No. 08/299,085
and was amended on _____
(if applicable)

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, §1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, §119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s)

Priority Claimed

(Number)	(Country)	(Day Month Year Filed)	<input type="checkbox"/> Yes	<input type="checkbox"/> No
(Number)	(Country)	(Day Month Year Filed)	<input type="checkbox"/> Yes	<input type="checkbox"/> No

I hereby claim the benefit under Title 35, United States Code, §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, §1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application.

07/987,555
(Application Serial No.)

12/08/92
(Filing Date)

abandoned
(Status)
(patented, pending, abandoned)

<u>07/501,092</u> (Application Serial No.)	<u>03/29/90</u> (Filing Date)	<u>abandoned</u> (Status) (patented, pending, abandoned)
<u>07/077,528</u> (Application Serial No.)	<u>07/24/87</u> (Filing Date)	<u>abandoned</u> (Status) (patented, pending, abandoned)
<u>PCT/US86/02269</u> (Application Serial No.)	<u>10/27/86</u> (Filing Date)	<u>abandoned</u> (Status) (patented, pending, abandoned)
<u>06/793,980</u> (Application Serial No.)	<u>11/01/85</u> (Filing Date)	<u>abandoned</u> (Status) (patented, pending, abandoned)
<u>07/142,039</u> (Application Serial No.)	<u>01/11/88</u> (Filing Date)	<u>abandoned</u> (Status) (patented, pending, abandoned)

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of first inventor, if any Randy R. Robinson	
First Inventor's signature	Date
Residence 133 Firestone Drive, Walnut Creek, California 94598	
Citizenship U.S.A.	
Post Office Address Same as residence	

Full name of second inventor, if any Alvin Y. Liu	
Second Inventor's signature	Date
Residence 4246 11 th Avenue, N.E., # 311, Seattle, WA 98105	
Citizenship U.S.A.	
Post Office Address Same as residence	
Full name of third inventor, if any Arnold H. Horwitz	
Third Inventor's signature	Date
Residence 7529 Midfield Avenue, Los Angeles, California 90045	
Citizenship U.S.A.	
Post Office Address Same as residence	
Full name of fourth inventor, if any Marc Better	
Fourth Inventor's signature	Date
Residence 2462 Zorada Drive, Los Angeles, California 90046	
Citizenship U.S.A.	
Post Office Address Same as residence	

Full name of fifth inventor, if any Randolph Wall	
Fifth Inventor's signature	Date
Residence 5106 Van Noord, Sherman Oaks, California 91423	
Citizenship U.S.A.	
Post Office Address Same as residence	
Full name of sixth inventor, if any Shau-Ping Lei	
Sixth Inventor's signature <i>Shau-Ping Lei</i>	Date 11-2-95
Residence 11452 Clarkson Road, Los Angeles, California 90064	
Citizenship ROC	
Post Office Address Same as residence	
Full name of seventh inventor, if any Gary L. Wilcox	
Seventh Inventor's signature	Date
Residence 2007 - 148th Street, S.E., Mill Creek, Washington 98012	
Citizenship U.S.A.	
Post Office Address Same as residence	

(Supply similar information and signature for subsequent joint inventors, if any)



Supplemental Declaration for Patent Application
English Language Declaration

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am an original, first and joint inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled

MODULAR ASSEMBLY OF ANTIBODY GENES, ANTIBODIES PREPARED THEREBY AND USE

the specification of which

(check one)

- ☐ is attached hereto.
- ☒ was filed on August 19, 1994 as
Application Serial No. 08/299,085
and was amended on _____
(if applicable)

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, §1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, §119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s)

Priority Claimed

(Number) (Country) (Day Month Year Filed)

☐ Yes ☐ No

(Number) (Country) (Day Month Year Filed)

☐ Yes ☐ No

I hereby claim the benefit under Title 35, United States Code, §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, §1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application.

07/987,555
(Application Serial No.)

12/08/92
(Filing Date)

abandoned
(Status)
(patented, pending, abandoned)

<u>07/501,092</u> (Application Serial No.)	<u>03/29/90</u> (Filing Date)	<u>abandoned</u> (Status) (patented, pending, abandoned)
<u>07/077,528</u> (Application Serial No.)	<u>07/24/87</u> (Filing Date)	<u>abandoned</u> (Status) (patented, pending, abandoned)
<u>PCT/US86/02269</u> (Application Serial No.)	<u>10/27/86</u> (Filing Date)	<u>abandoned</u> (Status) (patented, pending, abandoned)
<u>06/793,980</u> (Application Serial No.)	<u>11/01/85</u> (Filing Date)	<u>abandoned</u> (Status) (patented, pending, abandoned)
<u>07/142,039</u> (Application Serial No.)	<u>01/11/88</u> (Filing Date)	<u>abandoned</u> (Status) (patented, pending, abandoned)

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of first inventor, if any Randy R. Robinson	
First Inventor's signature	Date
Residence 133 Firestone Drive, Walnut Creek, California 94598	
Citizenship U.S.A.	
Post Office Address Same as residence	

Full name of second inventor, if any Alvin Y. Liu	
Second Inventor's signature	Date
Residence 4246 11 th Avenue, N.E., # 311, Seattle, WA 98105	
Citizenship U.S.A.	
Post Office Address Same as residence	
Full name of third inventor, if any Arnold H. Horwitz	
Third Inventor's signature	Date
Residence 7529 Midfield Avenue, Los Angeles, California 90045	
Citizenship U.S.A.	
Post Office Address Same as residence	
Full name of fourth inventor, if any Marc Better	
Fourth Inventor's signature	Date
Residence 2462 Zorada Drive, Los Angeles, California 90046	
Citizenship U.S.A.	
Post Office Address Same as residence	

Full name of fifth inventor, if any Randolph Wall	
Fifth Inventor's signature	Date
Residence 5106 Van Noord, Sherman Oaks, California 91423	
Citizenship U.S.A.	
Post Office Address Same as residence	
Full name of sixth inventor, if any Shau-Ping Lei	
Sixth Inventor's signature	Date
Residence 11452 Clarkson Road, Los Angeles, California 90064	
Citizenship ROC	
Post Office Address Same as residence	
Full name of seventh inventor, if any Gary L. Wilcox	
Seventh Inventor's signature <i>Gary L. Wilcox</i>	Date 11/1/95
Residence 2007 - 148th Street, S.E., Mill Creek, Washington 98012	
Citizenship U.S.A.	
Post Office Address Same as residence	

(Supply similar information and signature for subsequent joint inventors, if any)